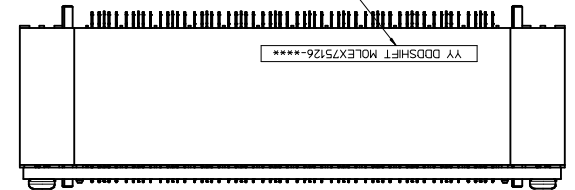


DATE CODE, MOLEX, PART NUMBER



NOTES:

1. MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94 V-0.
WAFER: LIQUID CRYSTAL POLYMER (LCP), 94 V-0, BLACK.
CONTACTS: COPPER ALLOY
HEXAGONAL THREADED INSERT: CARBON STEEL
MACHINE SCREW: CARBON STEEL
2. THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
3. THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
4. THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC. PS-45499-002.
5. RECOMMENDED DRILL SIZE: 0.66±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
6. USE APPLICATION TOOL 62202XXXX WHEN INSERTING INTO PCB.
7. RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THCKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

CONVERT TO LEAD-FREE EC NO: UCP2013-1884 2012/11/12 DRAWN BY: J BARRA CHKD: J BARRA APPR: MILLER 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	☉
	▽=0	4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- 0 PLACE ± ±	DRAWN BY: KSTILES DATE: 7/16/2003 CHECKED BY: DATE DSCHMIDG 7/16/2003 APPROVED BY: DATE MBANKIS 7/16/2003	TITLE	PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING	
	▽=0	ANGULAR ±1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE D	MATERIAL NO. SEE TABLE DOCUMENT NO. SD-75126-002	SHEET NO. 1 OF 3	

CIRCUIT SIZE	ITEM NUMBER	PLATEAU HS DOCK™	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	PLATING FINISH	CONNECTOR WAFER TYPE
108			90.50 3.563	81.50 3.209	89.00 3.504	75.62 2.977	99.40 3.913	71.00±0.08 2.795±.003	66.00±0.08 2.598±.003	FINISH 1	WELDED
144	75126-2001	75018-3023	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-2101	75018-3123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 2	
144	75126-4001	75018-3123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-8101	75018-8123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 3	

1. PLATING FINISH:

FINISH 1: (PREVIOUSLY TIN-LEAD)

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
COPPER UNDERPLATE OVERALL

FINISH 2:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
COPPER UNDERPLATE OVERALL

FINISH 3:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
NICKEL UNDERPLATE OVERALL

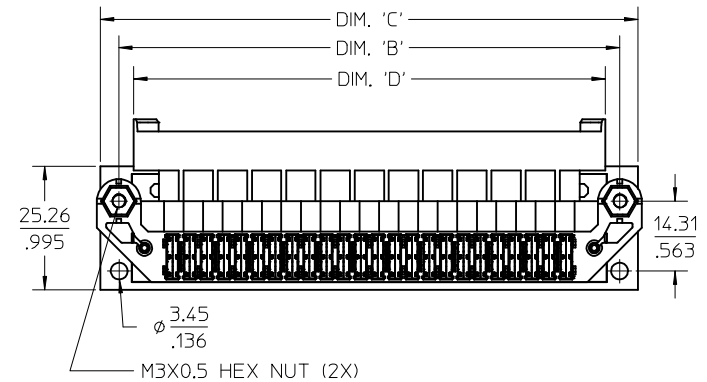
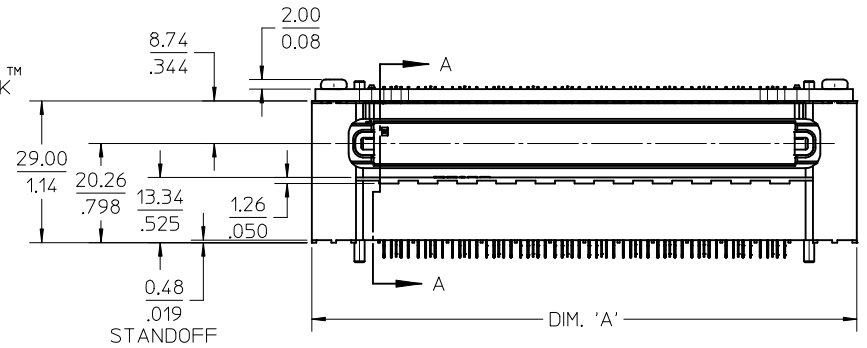
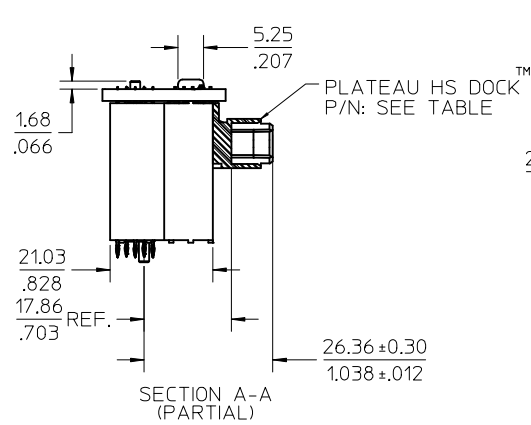
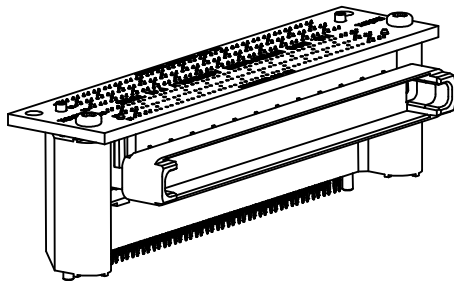
COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
NICKEL UNDERPLATE OVERALL

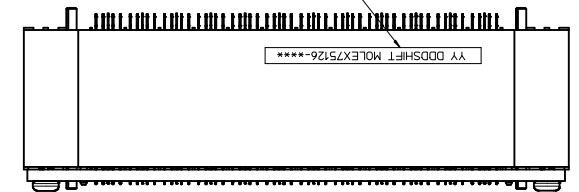
HOUSING

3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
COPPER UNDERPLATE OVERALL

SEE SHEET 1 EEC NO: UCP2013-1884 DRAWN BY: J. BARRA CHKD: J. BARRA APPR: SMILLER 2012/11/12 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ±.010	MM/IN	2:1	METRIC	
	▽=0	3 PLACES ±.025				
	▽=0	2 PLACES ±.050				
		ANGULAR ±1/2°				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
			DRAWN BY: KSTILES	DATE: 7/16/2003	TITLE: PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING	
			CHECKED BY: DSCHMIDG	DATE: 7/16/2003	molex	
			APPROVED BY: MBANKIS	DATE: 7/16/2003	DOCUMENT NO. SD-75126-002	
			MATERIAL NO.	DATE	SHEET NO. 2 OF 3	
			SIZE: D	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



DATE CODE, MOLEX, PART NUMBER



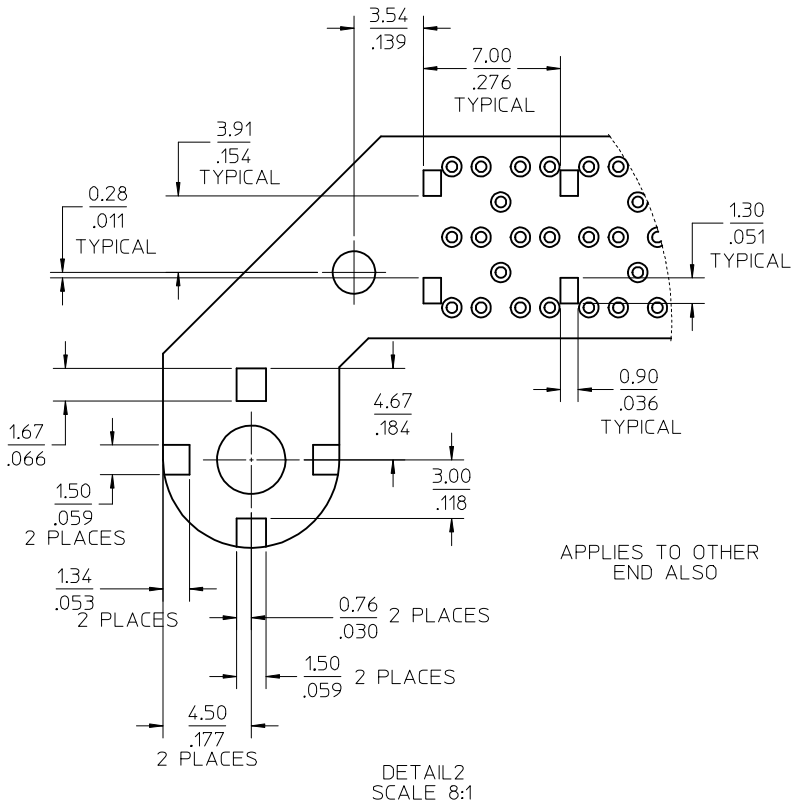
CIRCUIT SIZE	ITEM NUMBER	PLATEAU HS DOCK™	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	CONNECTOR WAFER TYPE
144	75126-8301	75018-5123	111.50/4.390	102.50/4.035	110.00/4.331	96.62/3.804	120.40/4.740	92.00±0.08/3.622±.003	87.00±0.08/3.425±.003	WELDLESS

NOTES:

- MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:
 HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94 V-0.
 WAFER: LIQUID CRYSTAL POLYMER (LCP), 94 V-0, BLACK.
 CONTACTS: COPPER ALLOY
 HEXAGONAL THREADED INSERT: CARBON STEEL
 MACHINE SCREW: CARBON STEEL
- PLATING FINISH:
 CONTACT INTERFACE
 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
 NICKEL UNDERPLATE OVERALL
 COMPLIANT INTERFACE
 0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
 NICKEL UNDERPLATE OVERALL
 HOUSING
 3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
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- THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
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- RECOMMENDED DRILL SIZE: 0.66±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
- USE APPLICATION TOOL 62202XXXX WHEN INSERTING INTO PCB.
- RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THCKNESS MIN.
 TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

INITIAL RELEASE EC NO: UCP2014-3379 DRAWN BY: TIBARRA 2014/02/13 CHKD BY: BARKER 2014/02/14 APPROV: SMILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm	MM/IN	2:1	METRIC	☉
	▽=0	INCH				
	▽=0	4 PLACES ±.010 3 PLACES ±.025 2 PLACES ±.050 1 PLACE ±.100 0 PLACE ±.150				
	ANGULAR ±1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRAWN BY: TIBARRA 2014/02/13 CHECKED BY: BARKER 2014/02/14 APPROVED BY: SMILLER 2014/03/13			TITLE PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING
			MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-75126-2000		SHEET NO. 1 OF 2
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

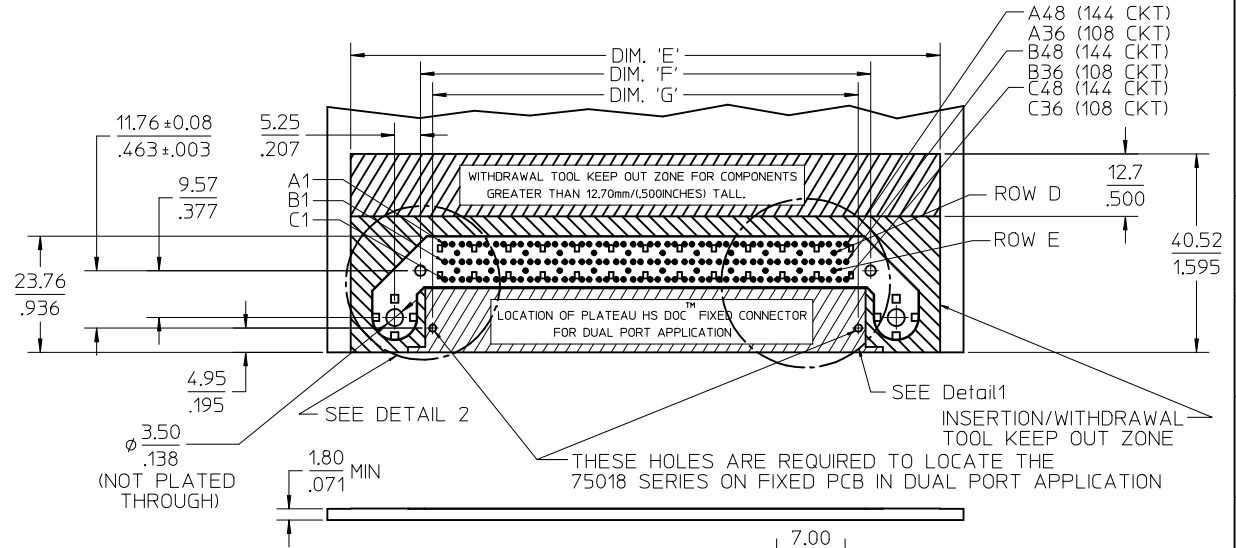
KEEP OUT AREA FOR STAND-OFFS



DETAIL2
SCALE 8:1

NOTE: THE DIMENSIONS DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

APPLIES TO OTHER END ALSO

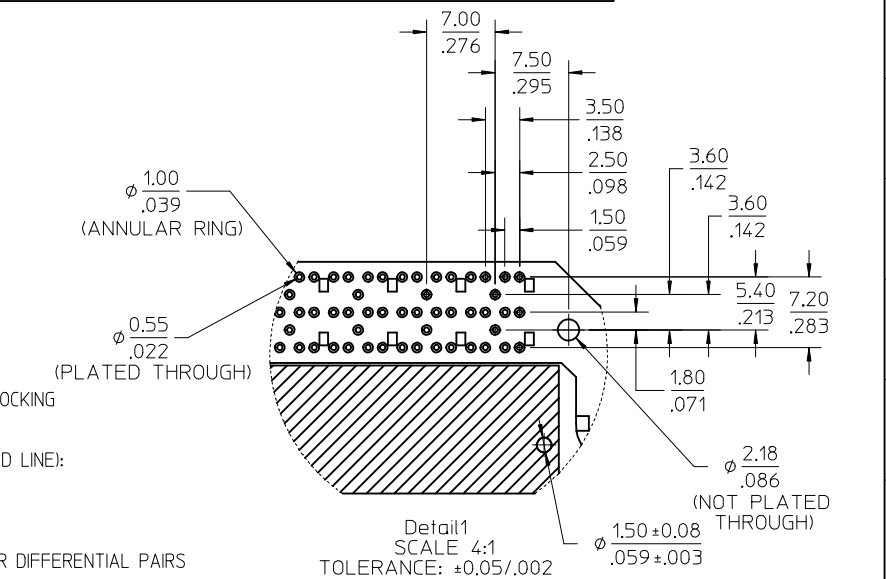


CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:

POWER CIRCUITS (15 AMPS PER INDICATED LINE):
A2-A1: POWER/RETURN,
A4-A3: POWER/RETURN,
C2-C1: POWER/RETURN

ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS
CURRENT CAPACITY: 300mA

GROUND CIRCUITS: ROWS D & E



Detail1
SCALE 4:1

TOLERANCE: ±0.05/-.002

SEE SHEET 1 EC NO: UCP2014-3379 DRAWN: T. BARRA 2014/02/13 CHKD: B. BARKER 2014/02/14 APPR: S. MILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0 ▽=0 ▽=0	mm INCH 4 PLACES ±.010 3 PLACES ±.025 2 PLACES ±.050 1 PLACE ±.100 0 PLACE ±.150	MM/IN	2:1	METRIC	☉
	ANGULAR ±1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.	DOCUMENT NO.	TITLE	
			SEE TABLE	SD-75126-2000	PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING	
					molex	
					SHEET NO. 2 OF 2	
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			